

/ Descriptions

SOD-523

Schottky Diode in a SOD-523 Plastic Package.

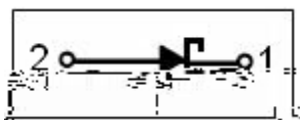
/ Features

Low forward voltage drop, HF Product.

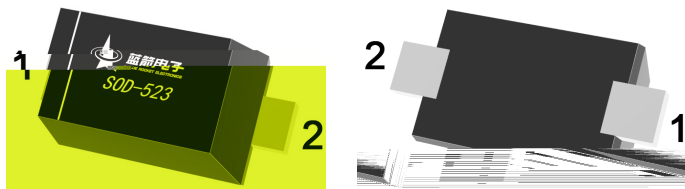
/ Applications

General purpose.

/ Equivalent Circuit



/ Pinning



PIN1: Cathode

PIN2: Anode

/ Marking

Type number	Marking code
RB520S-30	B

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	30	V
Forward Continuous Current	I_F	200	mA
Non-Repetitive Peak Forward Surge Current @t = 8.3ms	I_{FSM}	1	A
Power dissipation	P_D	200	mW
Junction Temperature	T_J	125	
Storage Temperature	T_{stg}	-55 to +125	

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test Conditions	Rating			Unit
			Min	Typ	Max	
Reverse Breakdown Voltage	V_{BR}	$I_R=500\mu A$	30			V
Forward Voltage	V_F	$I_F=200mA$			0.60	V
Peak Reverse Current	I_R	$V_R=10V$			1.0	μA

/ **Electrical Characteristic Curve**

Fig 1 Power Derating Curve

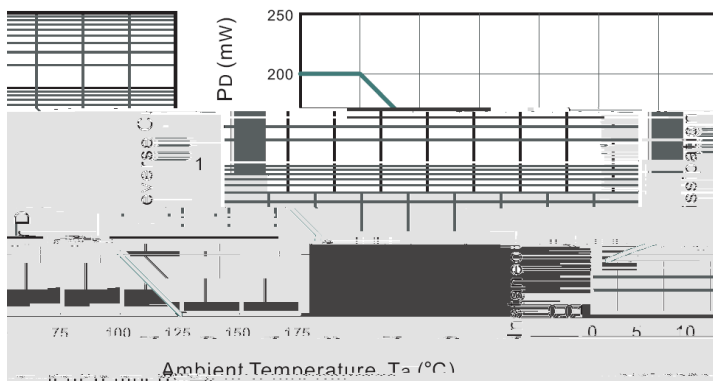
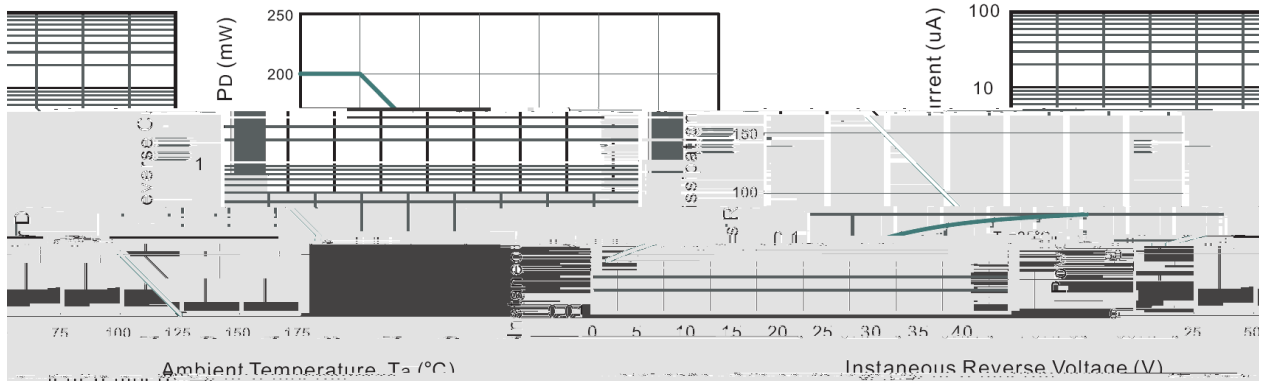


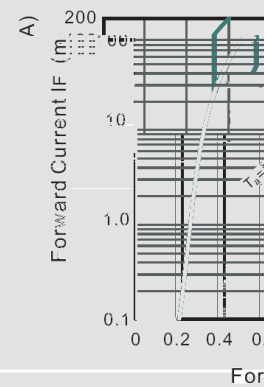
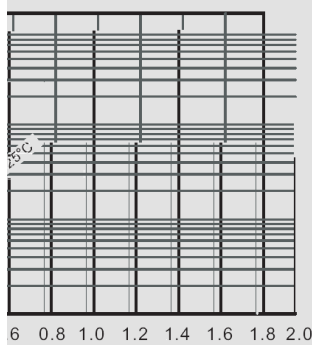
Fig 2 Typical Instantaneous Reverse

Characteristics



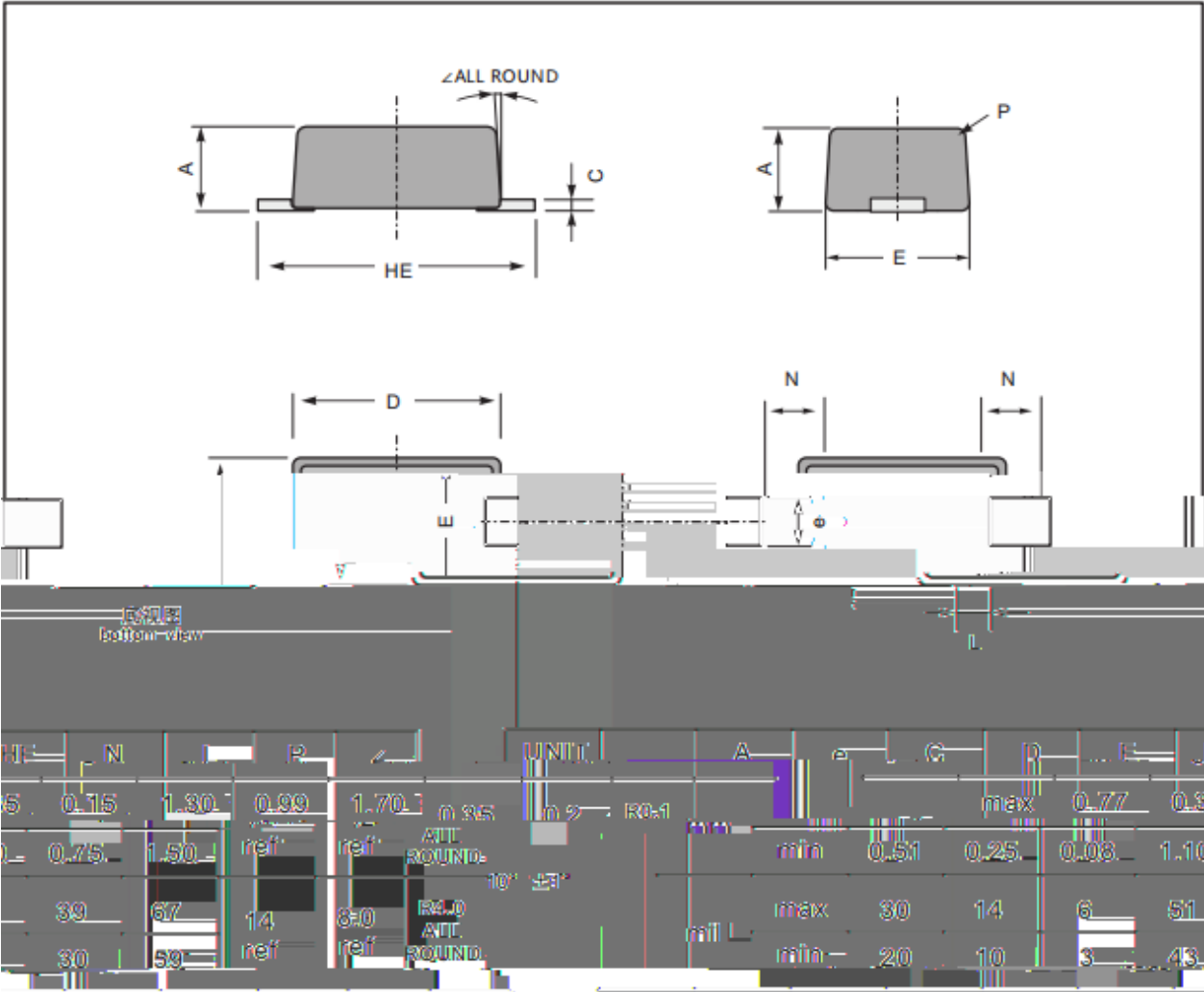
Forward Characteristic

Fig.3 Typical Fo

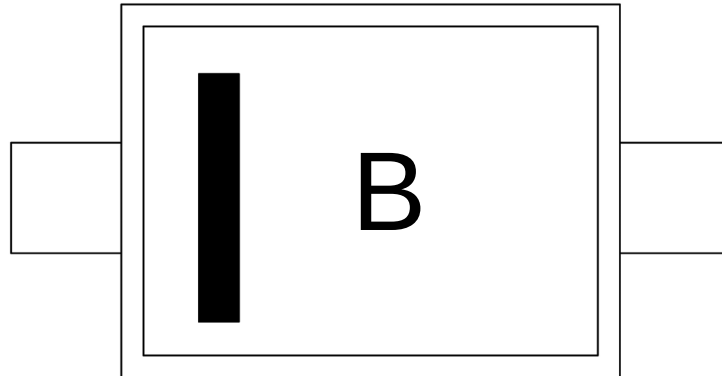


/ Package Dimensions

SOD-523



/ Marking Instructions

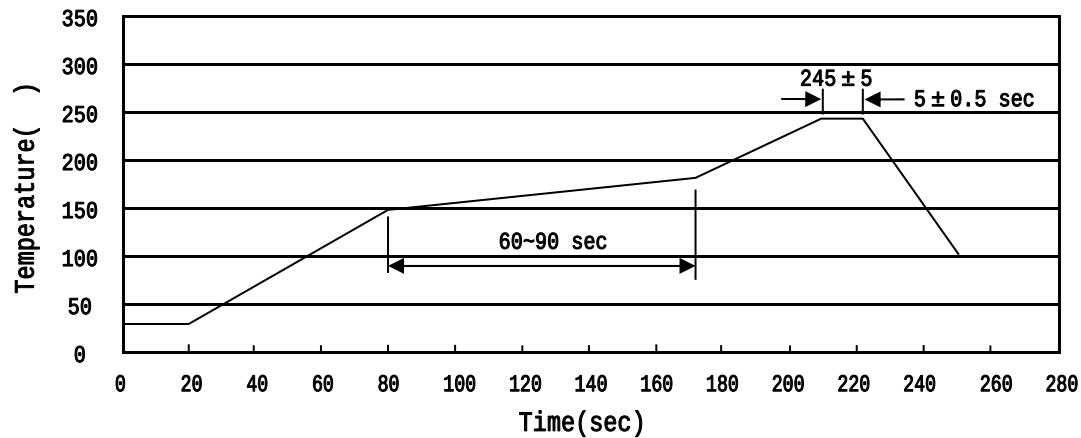


B

Note:

B : Product Type

() / **Temperature Profile for IR Reflow Soldering(Pb-Free)**



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ **Resistance to Soldering Heat Test Conditions**

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ **Packaging SPEC.**

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
SOD-523	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ **Notices**